

### IN THE CLAIMS

Please amend the application as follows:

Claims 1-2 (Canceled)

3. (Currently amended) A planarizing support layer provided on a bumped surface of one of a bumped-die and bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder ~~remainder~~ portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

4. (Previously Presented) A planarizing support layer provided on a bumped surface of one of a bumped-die and bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

5. (Original) A support layer as claimed in claim 4, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

6. (Currently amended) A support layer as claimed in claim 4, the under-fill layer being of a ~~predetermined~~ thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps during any mounting/under-fill process.

7. (Previously Presented) A support layer as claimed in claim 4, the under-fill layer comprising a polymer material.
8. (Previously Presented) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.
9. (Previously Presented) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.
10. (Previously Presented) A support layer as claimed in claim 4, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.

Claims 11-12 (Canceled)

13. (Currently amended) A back-grind/mounting arrangement comprising one of a bumped-die and bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and  
an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder ~~remainder~~ portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

14. (Currently amended) An arrangement as claimed in claim 13, the arrangement further comprising a secondary under-fill layer to under-fill at least one of: the remainder ~~remainder~~

portion of the bump-bodies not covered by the under-fill layer, and structures other than the bumps as encountered during any mounting process.

15. (Previously Presented) A back-grind/mounting arrangement comprising one of a bumped-die and bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies bumps on the bumped surface.
16. (Original) An arrangement as claimed in claim 15, the support layer further comprising an adhesive protection tape applied to the under-fill layer.
17. (Currently amended) An arrangement as claimed in claim 15, the under-fill layer being of a ~~predetermined~~ thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.
18. (Previously Presented) An arrangement as claimed in claim 15, the under-fill layer comprising a polymer material.
19. (Previously Presented) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.
20. (Previously Presented) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.

21. (Previously Presented) An arrangement as claimed in claim 15, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.

22. (Previously Presented) An arrangement as claimed in claim 15, wherein the arrangement is a flip-chip back-grind/mounting arrangement.

Claims 23-24 (Canceled)

25. (Currently amended) A back-grind/mounting method useable with either one of a bumped-die and bumped wafer, the method comprising: providing a planarizing support layer on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder ~~remainder~~ portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

26. (Currently amended) A method as claimed in claim 25, the method further comprising: providing a secondary under-fill layer to under-fill at least one of: the remainder ~~remainder~~ portion of the bump-bodies not covered by the under-fill layer, and structures other than the bumps as encountered during any mounting process.

27. (Original) A back-grind/mounting method useable with either one of a bumped-die and bumped wafer, the method comprising: providing a planarizing layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill support layer on a bumped surface of the bumped-

die or bumped-wafer, the support material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

28. (Original) A method as claimed in claim 27, the support layer further comprising an adhesive protection tape applied to the under-fill layer.
29. (Currently amended) A method as claimed in claim 27, the under-fill layer being of a ~~predetermined~~ thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.
30. (Previously Presented) A method as claimed in claim 27, the under-fill layer comprising a polymer material.
31. (Previously Presented) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.
32. (Previously Presented) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.
33. (Previously Presented) A method as claimed in claim 27, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.
34. (Previously Presented) A method as claimed in claim 27, wherein the method is a flip-chip back-grind/mounting method.